

Abstract

A semiconductor processing tape that shows low thermal shrinkage rate and shrinks evenly regardless of the direction of the tape so that the kerf width extends evenly without wrinkles or displacement in chip position occurring is provided.

The thermal shrinkage rates in both the lengthwise direction and the widthwise direction of the semiconductor processing tape are 0% or more to 20% or less when heated at 100 °C for 10 seconds. When the thermal shrinkage rate of either the lengthwise direction or the widthwise direction is 0.1% or more, the thermal shrinkage rate in the lengthwise direction divided by the thermal shrinkage rate in the widthwise direction is 0.01 or more to 100 or less (in the equation, thermal shrinkage rate = (size before heating – size after heating)/size before heating x 100(%)).